Unit: mm

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π–MOSV)

# 2SK3313

# Chopper Regulatorand DC-DC Converter Applications Motor Drive Applications

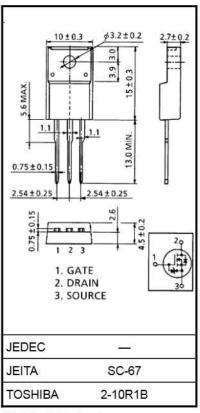
• Fast reverse recovery time  $t_{rr} = 90 \text{ ns (typ.)}$ 

• Built-in high-speed free-wheeling diode

 $\begin{array}{ll} \bullet & Low\ drain-source\ ON\ resistance & : R_{DS}\ (oN) = 0.5\ \Omega\ (typ.) \\ \bullet & High\ forward\ transfer\ admittance & : |Y_{fs}| = 8.5\ S\ (typ.) \\ \bullet & Low\ leakage\ current & : I_{DSS} = 100\ \mu A\ (max)\ (V_{DS} = 500\ V) \\ \bullet & Enhancement\ mode & : V_{th} = 2.0 \sim 4.0\ V\ (V_{DS} = 10\ V,\ I_D = 1\ mA) \end{array}$ 

## Absolute Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit
Drain-source voltage		V <sub>DSS</sub>	500	V
Drain-gate voltage (R <sub>GS</sub> = 20 kΩ)		VDGR	500	V
Gate-source voltage		V <sub>GSS</sub>	±30	٧
Drain current	DC (Note 1)	ID	12	Α
	Pulse (Note 1)	IDP	48	Α
Drain power dissipation (Tc = 25°C)		PD	40	W
Single pulse avalanche energy (Note 2)		EAS	324	mJ
Avalanche current		I <sub>AR</sub>	12	Α
Repetitive avalanche energy (Note 3)		EAR	4.0	mJ
Channel temperature		T <sub>ch</sub>	150	°C
Storage temperature range		T <sub>stg</sub>	-55~150	°C



Weight: 1.9 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

### Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R <sub>th (ch-c)</sub>	3.125	°C/W
Thermal resistance, channel to ambient	R <sub>th (ch-a)</sub>	62.5	°C/W

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2:  $V_{DD}$  = 90 V,  $T_{ch}$  = 25°C (initial), L = 3.83 mH,  $R_G$  = 25  $\Omega$ ,  $I_{AR}$  = 12 A

Note 3: Repetitive rating: Pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device.

Please handle with caution.



# Electrical Characteristics (Ta = 25°C)

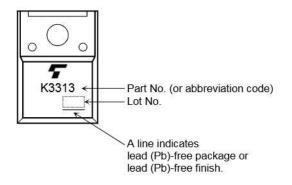
Chara	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	urrent	I <sub>GSS</sub>	V <sub>GS</sub> = ±25 V, V <sub>DS</sub> = 0 V	<u>(2</u> _3)	2_3	±10	μА
Gate-source br	eakdown voltage	V (BR) GSS	I <sub>G</sub> = ±100 μA, V <sub>DS</sub> = 0 V	±30	823	2_2	V
Drain cut-off cu	rrent	I <sub>DSS</sub>	V <sub>DS</sub> = 500 V, V <sub>GS</sub> = 0 V	, <del>72 -</del> 8	. =	100	μΑ
Drain-source b	reakdown voltage	V (BR) DSS	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V	500	=	-	٧
Gate threshold	voltage	V <sub>th</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	2.0	====	4.0	٧
Drain-source O	N resistance	R <sub>DS</sub> (ON)	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 6 A		0.5	0.62	Ω
Forward transfe	r admittance	Y <sub>fs</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 6 A	3.0	8.5	-	S
Input capacitance  Reverse transfer capacitance		C <sub>iss</sub>	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz		2040	-	pF
		C <sub>rss</sub>		===	210	==	
Output capacitance		Coss		5 <del>5 -</del> 8	630	-	
Switching time	Rise time	tr	$V_{GS}$ $V_{OUT}$ $V_{GS}$ $V_{OUT}$ $V_{GS}$ $V_{OUT}$ $V_{GS}$ $V_{OUT}$ $V_{GS}$ $V_{OUT}$		22	===	ns
	Turn-on time	ton		<del>2</del> 4	58	-	
	Fall time	t <sub>f</sub>		-	36	_	
	Turn-off time	t <sub>off</sub>	$V_{\mathrm{DD}} \stackrel{\Leftarrow}{=} 200 \mathrm{V}$ Duty $\leq 1\%$ , $t_{\mathrm{w}} = 10 \mu \mathrm{s}$	-	180	_	
Total gate charge (Gate-source plus gate-drain)		Qg	V <sub>DD</sub> ≈ 400 V, V <sub>GS</sub> = 10 V, I <sub>D</sub> = 12 A	<del>5-</del> 4	45	=	nC
Gate-source charge		Qgs			25	_	
Gate-drain ("miller") charge		Q <sub>gd</sub>	1	<del>2-</del> 8	20	-	5

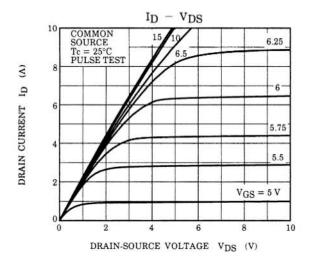
# Source-Drain Ratings and Characteristics (Ta = 25°C)

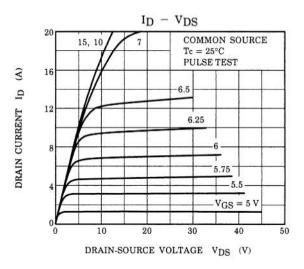
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I <sub>DR</sub>	=	-	-	12	А
Pulse drain reverse current (Note 1)	IDRP	1	<u>=</u> 0	<u></u>	48	Α
Forward voltage (diode)	V <sub>DSF</sub>	I <sub>DR</sub> = 12 A, V <sub>GS</sub> = 0 V	, <del>se s</del> a	. ==0	-1.7	V
Reverse recovery time	t <sub>rr</sub>	I <sub>DR</sub> = 12 A, V <sub>GS</sub> = 0 V	<u> </u>	90	160	ns
Reverse recovery charge	Qrr	dl <sub>DR</sub> / dt = 100 A / μs	52-73	0.25	: :=::	μC

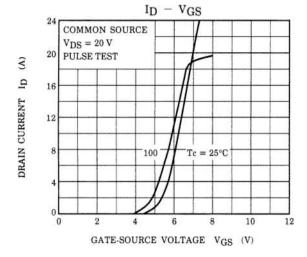
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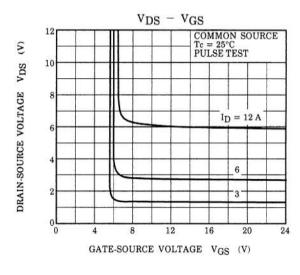
# Marking

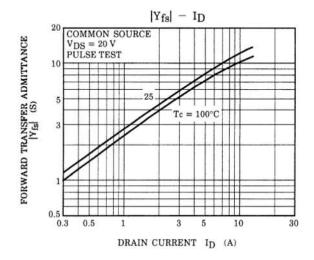


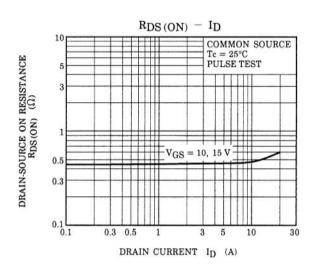


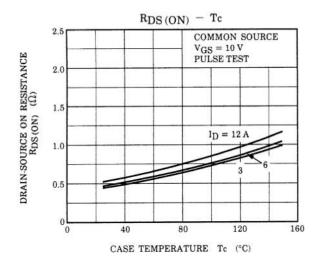


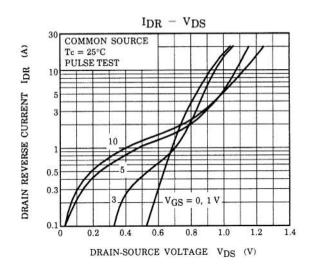


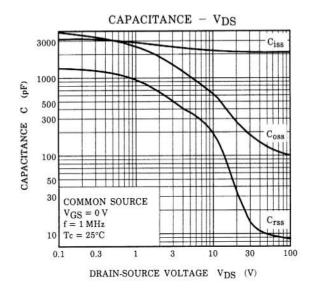


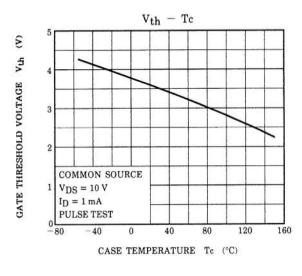


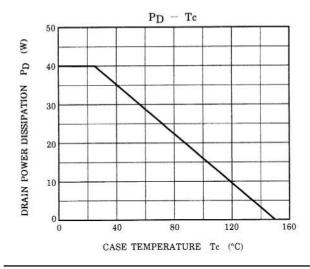


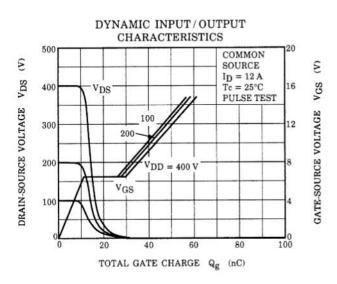




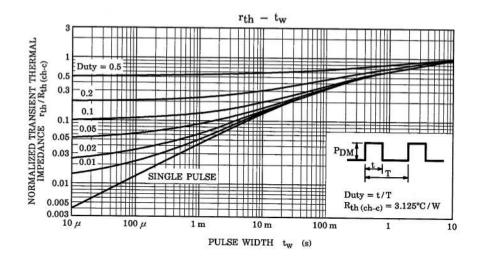


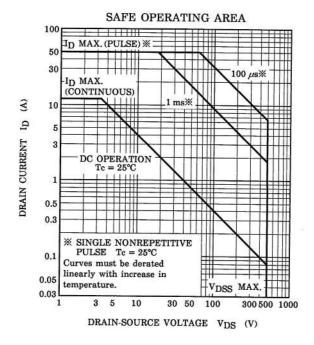


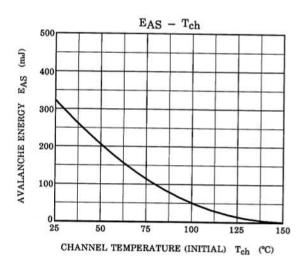


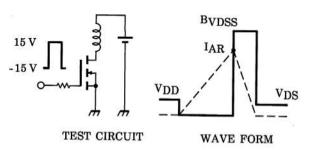


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$$\begin{aligned} R_G &= 25~\Omega \\ V_{DD} &= 90~V,~L = 3.83~mH \end{aligned} \quad E_{AS} &= \frac{1}{2} \cdot L \cdot I^2 \cdot \left( \frac{BVDSS}{BVDSS - V_{DD}} \right) \end{aligned}$$

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